What is claimed is:

1. An apparatus comprising:

a first signal path connected to a first plane via a plated hole;

a first metal flood connected to the plated hole to form a first plate;

a second signal path on a second plane; and

a second metal flood connected to the second signal path to form a second plate above the first plate.

2. The apparatus of claim 1 wherein the first and second plates form a capacitance.

3. The apparatus of claim 1 wherein the first plate is connected at one of a first receiver end and a first driver end of the first signal path.

4. The apparatus of claim 1 wherein the second plate is connected at one of a second receiver end and a second driver end of the second signal path.

5. The apparatus of claim 4 wherein the first and second signal paths are adjacent to each other.

6. The apparatus of claim 1 wherein the first plane is one of a ground plane and a power plane.

7. The apparatus of claim 6 wherein the first metal flood is an isolated area in the first plane.

8. A method comprising:

connecting a first signal path to a first plane via a plated hole;

forming a first plate by connecting a first metal flood to the plated hole; and

connecting a second metal flood to a second signal path on a second plane to form a second plate above the first plate.

9. The method of claim 8 wherein the first and second plates form a capacitance.

10. The method of claim 8 wherein the first plate is connected at one of a first receiver end and a first driver end of the first signal path.

11. The method of claim 8 wherein the second plate is connected at one of a second receiver end and a second driver end of the second signal path.

12. The method of claim 11 wherein the first and second signal paths are adjacent to each other.

13. The method of claim 8 wherein the first plane is one of a ground plane and a power plane.

14. The method of claim 13 wherein the first metal flood is an isolated area in the first plane.

15. A system comprising:

a through hole component to hold a component that is mounted on a board, the through hole component having one of a first receiver end and a first driver end; a signal carrying module coupled to the through hole component to carry signal, the signal carrying module comprising:

a first signal path connected to a first plane via a plated hole;

a first metal flood connected to the plated hole to form a first plate;

a second signal path on a second plane; and

a second metal flood connected to the second signal path to form a second plate above the first plate.

16. The system of claim 15 wherein the first and second plates form a capacitance.

17. The system of claim 15 wherein the first plate is connected at one of the first receiver end and the first driver end of the first signal path.

18. The system of claim 15 wherein the second plate is connected at one of a second receiver end and a second driver end of the second signal path.

19. The system of claim 18 wherein the first and second signal paths are adjacent to each other.

20. The system of claim 15 wherein the first plane is one of a ground plane and a power plane.

21. The system of claim 20 wherein the first metal flood is an isolated area in the first plane.